

Silicon PIN Diodes

Rev. V1

Features

- Non-Magnetic Ceramic Surface Mount Package
- Low Series Resistance
- Low Junction Capacitance
- Low Thermal Resistance
- RoHS* Compliant

Description

The MMP70xx-128-1 and MMP70xx-128-4 MELF PIN Diode Series are manufactured using a proprietary diode process which optimizes the anode and cathode bonding area of the diode to the adjacent heat spreading metal posts within the ceramic package. This unique geometry provides lower electrical and thermal resistance within the surface mount package to provide higher average power performance to comparable surface mount diode packages.

With lower thermal resistance (<20°C/W), RF C.W. incident power levels of 50 dBm and RF peak incident power levels of 60 dBm are very achievable in higher power UHF cold switching applications. The low series resistance (<1 Ω), coupled with the longer minority carrier lifetime, (>8 μ s), provides better IIP3 distortion values >70 dBm, for SP2T T_x & R_x Switches.

These devices are hermetically sealed and are constructed with non-magnetic materials to meet the stringent requirements for MRI systems. The devices are RoHS compliant.

The MMP70xx-128-1 and MMP70xx-128-4 MELF PIN Diode Series are designed to be used in High Average Power Switch and Attenuator applications, operating from 1 MHz to 1 GHz at Incident Power levels of 100 W Average Power and 1 KW Peak Power. These devices are durable, reliable, and are capable of meeting all military, commercial, and industrial applications.



Ordering Information

Part Number	Package	
MMP70xx-128-1-R	2000 piece reel	
MMP70xx-128-4-R	500 piece reel	

Environmental Capabilities

The MMP70xx-128-x Series of PIN diodes are capable of meeting the environmental requirements of MIL-STD-750.

Static & Moisture Sensitivity

These electronic devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these (HBM) Class 1A devices. The moisture sensitivity level rating for this device is MSL1.

1

^{*} Restrictions on Hazardous Substances, European Union Directive 2011/65/EU.



Silicon PIN Diodes

Rev. V1

Electrical Specifications:

 $T_A = +25^{\circ}C$, $V_F = 1 \text{ V max.}$ @ 100 mA, $I_R = 1 \text{ }\mu\text{A}$ max. @ 80% V_B

Model	Reverse Voltage Breakdown @ 10 µA (V _{BR})	Total Capacitance @ 100 V, 1 MHz (C _T)	Minority Carrier Lifetime I _F = 10 mA, I _R = 6 mA (T _L)	Series Resistance @ 100 mA, 100 MHz (R _S)	Parallel Resistance @ 0 V, 100 MHz (R _P)	C.W. Thermal Resistance
	V	pF	μs	Ω	kΩ	°C/W
	Min.	Max.	Тур.	Max.	Тур.	Max.
MMP7070-128-4	100	2.2	6.0	0.5	20	20
MMP7071-128-4	100	2.0	8.0	1.0	50	20
MMP7072-128-1	100	0.7	3.0	0.8	200	20
MMP7073-128-1	100	1.0	2.5	0.5	100	20
MMP7074-128-4	200	2.2	6.0	0.5	20	20
MMP7075-128-4	200	2.0	8.0	1.0	50	20
MMP7076-128-1	200	0.7	3.0	0.8	200	20
MMP7077-128-1	200	1.0	2.5	0.5	100	20
MMP7078-128-1	400	1.0	2.5	0.5	100	20
MMP7079-128-4	600	2.2	6.0	0.5	20	20
MMP7080-128-1	600	0.7	3.0	0.8	200	20
MMP7081-128-1	50	1.2	4.0	0.8	20	20
MMP7089-128-1	500	0.5	1.0	0.6	10	30
MMP7090-128-1	500	0.7	2.0	0.5	20	25
MMP7091-128-1	500	1.0	3.0	0.3	50	15

Absolute Maximum Ratings

Parameter	Absolute Maximum	
Forward Current	1000 mA	
Forward Voltage	1.2 V @ I _F = 100 mA	
Power Dissipation	$30 \text{ W},$ Infinite heat sink; $T_C = +25^{\circ}\text{C},$ De-Rate Linearly @ -200 mW/ $^{\circ}\text{C}$ from 7.5 W @ +25 $^{\circ}\text{C}$ to 0 W @ $T_J = +175^{\circ}\text{C}$	
Junction Temperature	+175°C	
Operating Temperature	-65°C to +125°C	
Storage Temperature	-65°C to +150°C	
Assembly Temperature	<260°C for 10 seconds	



Silicon PIN Diodes

Rev. V1

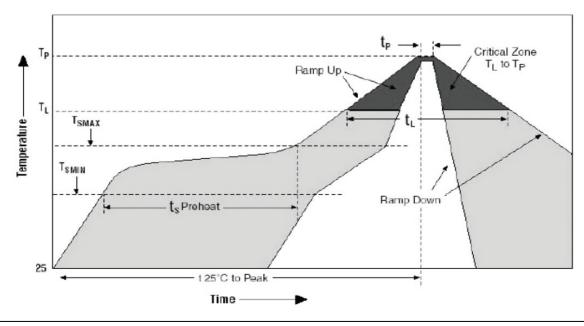
Assembly Instructions

MELF PIN Diodes may be placed onto circuit boards with pick and place manufacturing equipment from tape-reel. The devices are attached to the circuit using conventional solder re-flow or wave soldering procedures with RoHS type or Sn 60 / Pb 40 type solders.

Table 1. Time-Temperature Profile for Sn60/Pb40 or RoHS Type Solders

Profile Feature	SnPb Solder Assembly	Pb-Free Solder Assembly
Average Ramp-Up Rate (T _L to T _P)	3°C /second maximum	3°C /second maximum
Preheat:		
- Temperature Min (T _{smin})	100°C	150°C
- Temperature Max (T _{smax})	150°C	200°C
- Time (min to max)(t _s)	60-120 s	60-180 s
T _{smax} to T _L - Ramp-Up Rate		3°C/s maximum
Time Maintained Above: - Temperature (T _L) - Time (t _L)	183°C 60-150 s	217°C 60-150 s
Peak temperature (T _p)	225 +0/-5°C	260 +0/-5°C
Time Within 5°C of Actual Peak Temperature (t _p)	10 – 30 s	20 – 40 s
Ramp-Down Rate	6°C /s maximum	6°C /s maximum
Time 25°C to Peak Temperature	6 minutes maximum	8 minutes maximum

Figure 1. Solder Re-Flow Time-Temperature Profile

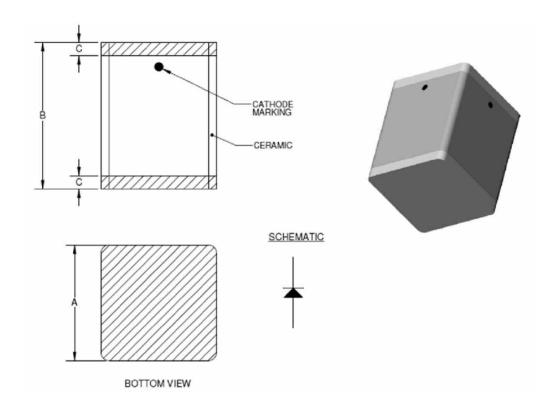




Silicon PIN Diodes

Rev. V1

Outline Drawing (CS128-1 & CS128-4)



Outline Dimensions

Case	Α	В	С
CS128-1	0.088 ±0.007	0.125 ±0.010	0.02
CS120-1	(2.24 ±0.18)	(3.18 ±0.25)	-0.51
CS128-4	0.143 +0.004 / -0.002	0.181 +0.003 / -0.002	0.016 ±0.008
	(3.63 +0.10 / -0.005)	(4.60 +0.08 / -0.05)	(0.41 ±0.20)



Silicon PIN Diodes

Rev. V1

MACOM Technology Solutions Inc. All rights reserved.

Information in this document is provided in connection with MACOM Technology Solutions Inc ("MACOM") products. These materials are provided by MACOM as a service to its customers and may be used for informational purposes only. Except as provided in MACOM's Terms and Conditions of Sale for such products or in any separate agreement related to this document, MACOM assumes no liability whatsoever. MACOM assumes no responsibility for errors or omissions in these materials. MACOM may make changes to specifications and product descriptions at any time, without notice. MACOM makes no commitment to update the information and shall have no responsibility whatsoever for conflicts or incompatibilities arising from future changes to its specifications and product descriptions. No license, express or implied, by estoppels or otherwise, to any intellectual property rights is granted by this document.

THESE MATERIALS ARE PROVIDED "AS IS" WITHOUT WARRANTY OF ANY KIND, EITHER EXPRESS OR IMPLIED, RELATING TO SALE AND/OR USE OF MACOM PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, CONSEQUENTIAL OR INCIDENTAL DAMAGES, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT. MACOM FURTHER DOES NOT WARRANT THE ACCURACY OR COMPLETENESS OF THE INFORMATION, TEXT, GRAPHICS OR OTHER ITEMS CONTAINED WITHIN THESE MATERIALS. MACOM SHALL NOT BE LIABLE FOR ANY SPECIAL, INDIRECT, INCIDENTAL, OR CONSEQUENTIAL DAMAGES, INCLUDING WITHOUT LIMITATION, LOST REVENUES OR LOST PROFITS, WHICH MAY RESULT FROM THE USE OF THESE MATERIALS.

MACOM products are not intended for use in medical, lifesaving or life sustaining applications. MACOM customers using or selling MACOM products for use in such applications do so at their own risk and agree to fully indemnify MACOM for any damages resulting from such improper use or sale.